

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPB-3227SURKCGKC	Hyper Red (AlGaInP)	Water Clear	120	250	100°
			*40	*80	
	Green (AlGaInP)		20	55	
			*20	*55	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.		Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	650 574	*645 *574		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570	*630 *570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20			nm	IF=20mA
C	Capacitance	Hyper Red Green	35 15			pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1		2.5 2.5	V	IF=20mA
IR	Reverse Current	Hyper Red Green			10 10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

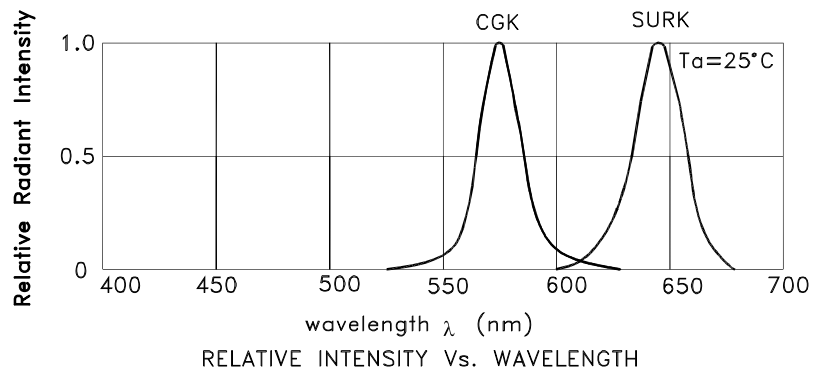
*Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

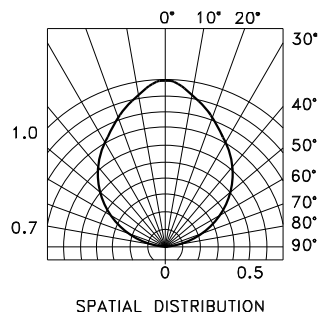
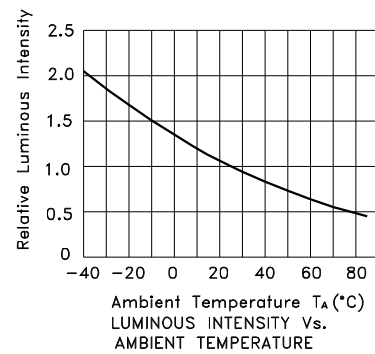
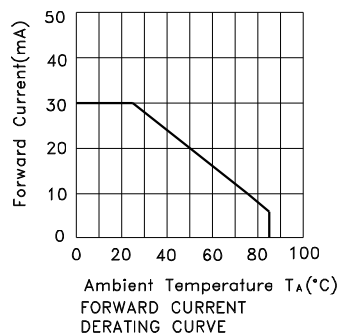
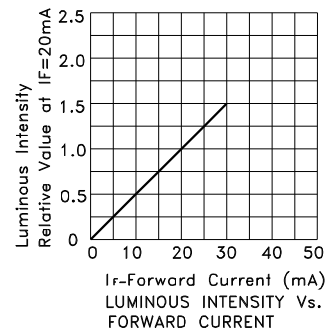
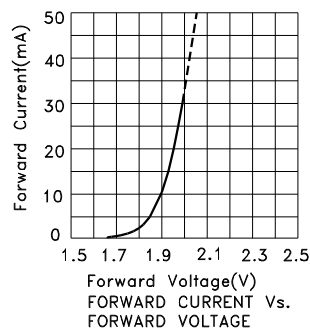
Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

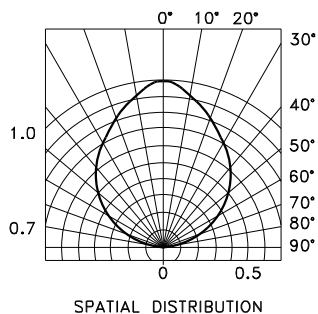
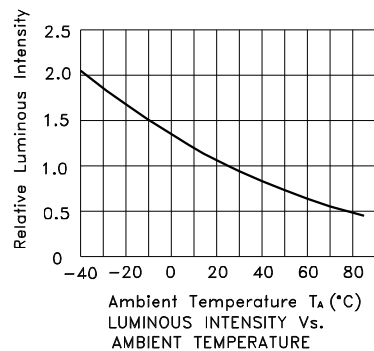
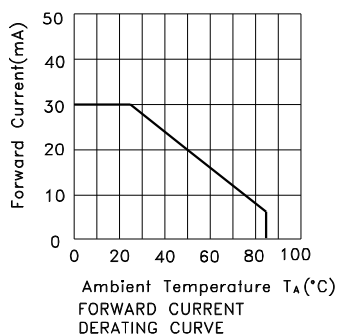
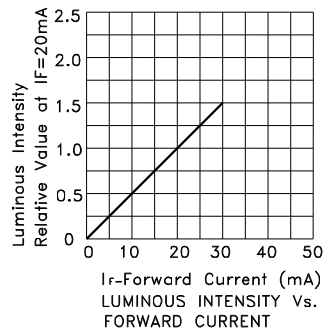
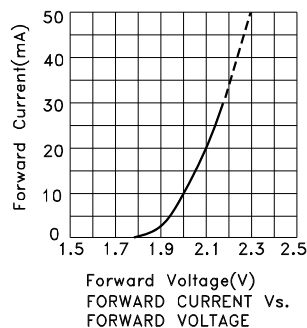
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPB-3227SURKCGKC Hyper Red



Green



KPB-3227SURKCGKC

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

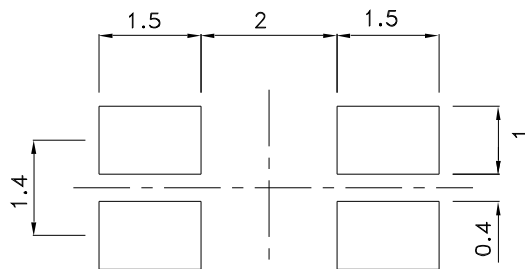
Reflow Soldering Profile For Lead-free SMT Process.



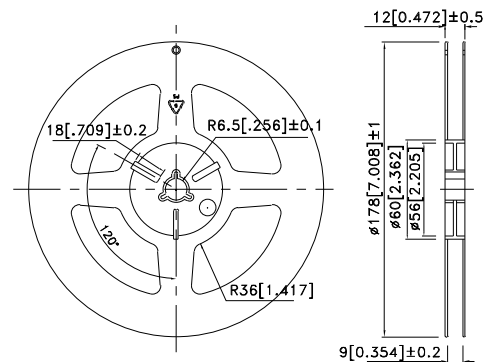
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

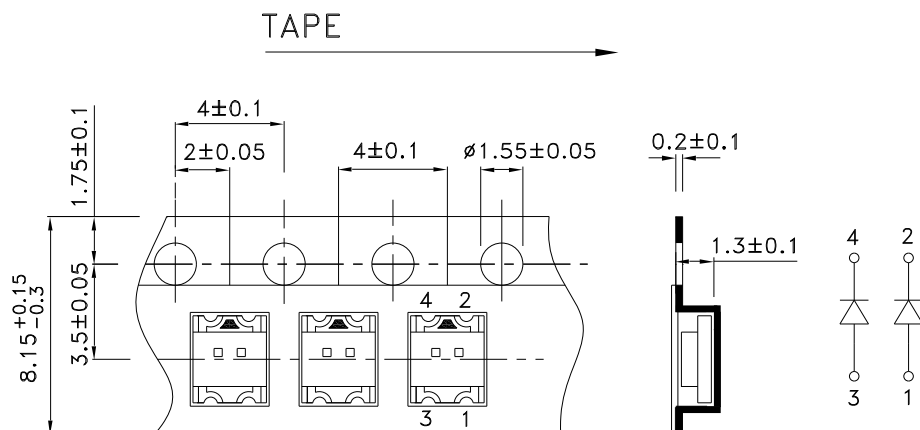
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

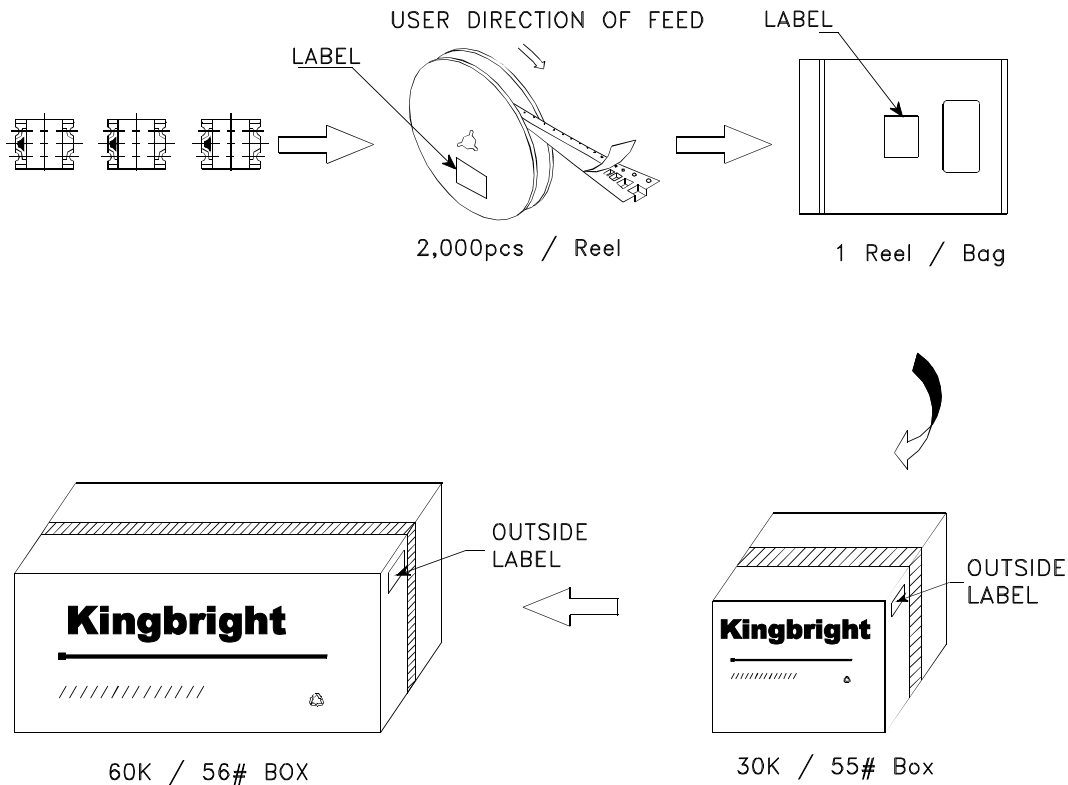



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

KPB-3227SURKCGKC



Kingbright	
P/NO: KPB-3227xxx	
QTY: 2,000 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	